



Nelco N4000-11

CAF Resistant, Low-CTE, High-Tg Multifunctional Epoxy Laminate & Prepreg

The Nelco N4000-11 is a CAF* resistant, high Tg (175° C by DSC) multifunctional epoxy dielectric substrate. This material is formulated to provide the PWB manufacturer and OEM with vastly improved thermal, mechanical, and electrical performance in lead-free assembly and high layer count, sophisticated PWB designs.

Key Features =

Tg >175°C, excellent thermal stability and moisture resistance

- Lead-free assembly compatibility
- Suitable for high-layer count, sophisticated PWB designs

CAF Resistant

- Providing long term reliability in end products

Low Z-axis expansion

- Reduced expansion improves through-hole reliability

Dicyandiamide (DICY) free, proprietary resin chemistry

- Extremely low Z-CTE.
- Improved thermal stability, CAF and moisture resistance when compared to traditional FR-4

Superior electrical properties

- Supporting advanced technology PWB designs

Optimized FR-4 processing

- Superior rheology providing consistent controlled flow and superior via topography.
- 75 min press at 185°C and 200-300 psi

And Much More

- Vacuum laminated
- Available in a wide variety of constructions, copper weights and glass styles including standard copper, double treat and RTFOIL® laminate.
- Meets UL 94V-0 and IPC-4101/83 and /98 specifications*
- All Nelco materials are RoHS compliant.
- * material also meets the specifications of the IPC-4101/26 unfilled slash sheet.

Applications

- Lead-Free Assembly Substrate
- Large Format Backplanes
- Tight Tolerance Via to Via Applications
- High I / O Count BGA Substrates
- Extreme Layer count Multilayers
- Lead-Free DCA Applications
- High Temperature Underhood Automotive
- Telecommunications Infrastructure
- Sophisticated Data Storage Applications

Global Availability

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Park's UL file number: E36295



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Property / Condition	Value (U.S. Units)		Value (Metric Units)		Test Method
Mechanical Properties					
Peel Strength - 1 oz. (35 micron) Cu					
After Solder Float	9.0	lb/inch	1.58	N/mm	IPC-TM-650.2.4.8
At Elevated Temperature	7.0	lb/inch	1.23	N/mm	IPC-TM-650.2.4.8.2a
After Exposure to Process Solutions	9.0	lb/inch	1.58	N/mm	IPC-TM-650.2.4.8
X/Y CTE [-40°C to +125°C]	12 - 14	ppm/°C	12 - 14	ppm/°C	IPC-TM-650.2.4.41
Z Axis CTE Alpha 1 [50°C to Tg]	65	ppm/°C	65	ppm/°C	IPC-TM-650.2.4.41
Z Axis CTE Alpha 2 [Tg to 260°C]	265	ppm/°C	265	ppm/°C	IPC-TM-650.2.4.41
Z Axis Expansion [50°C to 260°C]	3.2	%	3.2	%	IPC-TM-650.2.4.41
Young's Modulus (X/Y)	4.4/3.7	psi x 10 ⁶	29.9/25.1	GN/m ²	ASTM D3039
Poisson's Ratios (X/Y)	0.16/0.14		0.16/0.14		ASTM D3039
Thermal Conductivity	0.4 - 0.6	W/mK	0.4 - 0.6	W/mK	ASTM E1461-92
Specific Heat	1.20 - 1.40	J/gK	1.20 - 1.40	J/gK	ASTM E1461-92
Electrical Properties					
Dielectric Constant (50% resin content)					
@ 1 MHz (TFC/LCR Meter)	4.3		4.3		IPC-TM-650.2.5.5.3
@ 1 GHz (RF Impedance)	4.1		4.1		IPC-TM-650.2.5.5.9
@ 2.5 GHz (Stripline)	3.8		3.8		IPC-TM-650.2.5.5.5
Dissipation Factor (50% resin content)					
@ 1 MHz (TFC/LCR Meter)	0.016		0.016		IPC-TM-650.2.5.5.3
@ 2.5 GHz (Stripline)	0.020		0.020		IPC-TM-650.2.5.5.5
Volume Resistivity					
C - 96/35/90	10 ⁷	$M\Omega$ - cm	107	$M\Omega$ - cm	IPC-TM-650.2.5.17.1
E - 24/125	10 ⁷	$M\Omega$ - cm	10 ⁷	$M\Omega$ - cm	IPC-TM-650.2.5.17.1
Surface Resistivity					
C - 96/35/90	106	$M\Omega$	106	ΜΩ	IPC-TM-650.2.5.17.1
E - 24/125	106	$M\Omega$	106	ΜΩ	IPC-TM-650.2.5.17.1
Electric Strength	1300	V/mil	5.1x10 ⁴	V/mm	IPC-TM-650.2.5.6.2
Dielectric Breakdown	>50	kV	>50	kV	IPC-TM-650.2.5.6
Arc Resistance	124	seconds	124	seconds	IPC-TM-650.2.5.1
Thermal Properties					
Glass Transition Temperature (T _g)					
DSC (°C)	>175	°C	>175	°C	IPC-TM-650.2.4.25c
TMA (°C)	170	°C	170	°C	IPC-TM-650.2.4.24c
Degradation Temp (TGA) (5% wt. loss)	345	°C	345	°C	IPC-TM-650.2.3.40
Pressure Cooker - 60 min then solder dip	_		_		IPC-TM-650.2.6.16
@288°C until failure (max 10 min.)	Pass		Pass		(modified)
^T 260	30	minutes	30	minutes	IPC-TM-650.2.4.24.1
Chemical/Physical Properties					
Moisture Absorption	0.15	wt. %	0.15	wt. %	IPC-TM-650.2.6.2.1
Methylene Chloride Resistance	0.8	% wt. chg.	0.8	% wt. chg.	IPC-TM-650.2.3.4.3
Density [50% resin content]	1.96	g/cm³	1.96	g/cm³	Internal Method

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All test data provided are typical values and not intended to be specification values. For review of critical specification tolerances, please contact a Nelco representative directly. Nelco reserves the right to change these typical values as a natural process of refining our testing equipment and techniques.

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^{*}CAF resistance has been established to greater than 500 hours using a specific OEM coupon design and test procedure. For details on this or other CAF tests, please visit www.parkelectro.com.

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